



# STP210NF02 STB210NF02 STB210NF02-1

N-CHANNEL 20V - 0.0026  $\Omega$  - 120A D PAK/I PAK/TO-220

STripFET™ II POWER MOSFET

AUTOMOTIVE SPECIFIC

| TYPE          | V <sub>DSS</sub> | R <sub>DS(on)</sub> | I <sub>D</sub> |
|---------------|------------------|---------------------|----------------|
| STB210NF02/-1 | 20 V             | <0.0032 $\Omega$    | 120 A(**)      |
| STP210NF02    | 20 V             | <0.0032 $\Omega$    | 120 A(**)      |

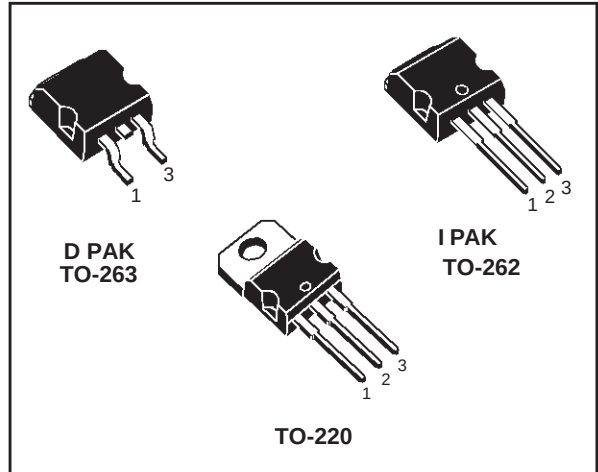
- TYPICAL R<sub>DS(on)</sub> = 0.0026 $\Omega$
- STANDARD THRESHOLD DRIVE
- 100% AVALANCHE TESTED

## DESCRIPTION

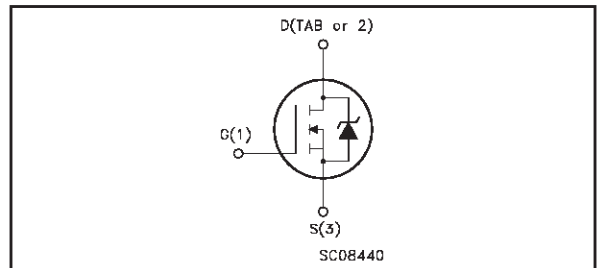
This Power MOSFET is the latest development of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

## APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SOLENOID AND RELAY DRIVERS
- MOTOR CONTROL, AUDIO AMPLIFIERS
- DC-DC & DC-AC CONVERTERS



## INTERNAL SCHEMATIC DIAGRAM



## Ordering Information

| SALES TYPE   | MARKING  | PACKAGE            | PACKAGING   |
|--------------|----------|--------------------|-------------|
| STB210NF02   | B210NF02 | D <sup>2</sup> PAK | TUBE        |
| STB210NF02T4 | B210NF02 | D <sup>2</sup> PAK | TAPE & REEL |
| STP210NF02   | P210NF02 | TO-220             | TUBE        |
| STB210NF02-1 | B210NF02 | I <sup>2</sup> PAK | TUBE        |

## ABSOLUTE MAXIMUM RATINGS

| Symbol              | Parameter                                             | Value      | Unit |
|---------------------|-------------------------------------------------------|------------|------|
| V <sub>DS</sub>     | Drain-source Voltage (V <sub>GS</sub> = 0)            | 20         | V    |
| V <sub>DGR</sub>    | Drain-gate Voltage (R <sub>GS</sub> = 20 k $\Omega$ ) | 20         | V    |
| V <sub>GS</sub>     | Gate- source Voltage                                  | $\pm 20$   | V    |
| I <sub>D</sub> (**) | Drain Current (continuous) at T <sub>C</sub> = 25°C   | 120        | A    |
| I <sub>D</sub>      | Drain Current (continuous) at T <sub>C</sub> = 100°C  | 120        | A    |
| I <sub>DM</sub> (•) | Drain Current (pulsed)                                | 480        | A    |
| P <sub>tot</sub>    | Total Dissipation at T <sub>C</sub> = 25°C            | 300        | W    |
|                     | Derating Factor                                       | 2.0        | W/°C |
| dv/dt (1)           | Peak Diode Recovery voltage slope                     | 1          | V/ns |
| E <sub>AS</sub> (2) | Single Pulse Avalanche Energy                         | 2.3        | J    |
| T <sub>stg</sub>    | Storage Temperature                                   | -55 to 175 | °C   |
| T <sub>j</sub>      | Operating Junction Temperature                        |            |      |

(•) Pulse width limited by safe operating area.

(\*\*) Current Limited by Package

(1) I<sub>SD</sub>  $\leq$  120A, di/dt  $\leq$  250A/ $\mu$ s, V<sub>DD</sub>  $\leq$  V<sub>(BR)DSS</sub>, T<sub>j</sub>  $\leq$  T<sub>JMAX</sub>

(2) Starting T<sub>j</sub> = 25 °C, I<sub>D</sub> = 60 A, V<sub>DD</sub> = 14 V

**STB210NF02/-1 STP210NF02****THERMAL DATA**

|                |                                                                                  |     |                     |      |
|----------------|----------------------------------------------------------------------------------|-----|---------------------|------|
| Rthj-case      | Thermal Resistance Junction-case                                                 | Max | 0.5                 | °C/W |
| Rthj-amb       | Thermal Resistance Junction-ambient                                              | Max | 62.5                | °C/W |
| Rthj-pcb       | Thermal Resistance Junction-pcb                                                  | Max | see curve on page 6 | °C/W |
| T <sub>I</sub> | Maximum Lead Temperature For Soldering Purpose<br>(for 10 sec. 1.6 mm from case) | Typ | 300                 | °C   |

**ELECTRICAL CHARACTERISTICS** (T<sub>case</sub> = 25 °C unless otherwise specified)**OFF**

| Symbol               | Parameter                                             | Test Conditions                                                                     | Min. | Typ. | Max.    | Unit     |
|----------------------|-------------------------------------------------------|-------------------------------------------------------------------------------------|------|------|---------|----------|
| V <sub>(BR)DSS</sub> | Drain-source Breakdown Voltage                        | I <sub>D</sub> = 250 µA V <sub>GS</sub> = 0                                         | 20   |      |         | V        |
| I <sub>DSS</sub>     | Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0) | V <sub>DS</sub> = Max Rating<br>V <sub>DS</sub> = Max Rating T <sub>C</sub> = 125°C |      |      | 1<br>10 | µA<br>µA |
| I <sub>GSS</sub>     | Gate-body Leakage Current (V <sub>DS</sub> = 0)       | V <sub>GS</sub> = ± 20V                                                             |      |      | ±100    | nA       |

**ON (\*)**

| Symbol              | Parameter                         | Test Conditions                                           | Min. | Typ. | Max. | Unit |
|---------------------|-----------------------------------|-----------------------------------------------------------|------|------|------|------|
| V <sub>GS(th)</sub> | Gate Threshold Voltage            | V <sub>DS</sub> = V <sub>GS</sub> I <sub>D</sub> = 250 µA | 2    |      | 4    | V    |
| R <sub>DS(on)</sub> | Static Drain-source On Resistance | V <sub>GS</sub> = 10 V I <sub>D</sub> = 50 A              |      | 2.6  | 3.2  | mΩ   |

**DYNAMIC**

| Symbol                                                   | Parameter                                                               | Test Conditions                                       | Min. | Typ.                | Max. | Unit           |
|----------------------------------------------------------|-------------------------------------------------------------------------|-------------------------------------------------------|------|---------------------|------|----------------|
| g <sub>fs</sub> (*)                                      | Forward Transconductance                                                | V <sub>DS</sub> = 10 V I <sub>D</sub> = 50 A          |      | 130                 |      | S              |
| C <sub>iss</sub><br>C <sub>oss</sub><br>C <sub>rss</sub> | Input Capacitance<br>Output Capacitance<br>Reverse Transfer Capacitance | V <sub>DS</sub> = 15V, f = 1 MHz, V <sub>GS</sub> = 0 |      | 5100<br>3500<br>800 |      | pF<br>pF<br>pF |

**ELECTRICAL CHARACTERISTICS** (continued)**SWITCHING ON**

| Symbol                        | Parameter                                                    | Test Conditions                                                                                                        | Min. | Typ.            | Max. | Unit           |
|-------------------------------|--------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------|------|-----------------|------|----------------|
| $t_{d(on)}$<br>$t_r$          | Turn-on Delay Time<br>Rise Time                              | $V_{DD} = 10\text{ V}$ $I_D = 60\text{ A}$<br>$R_G = 4.7\ \Omega$ $V_{GS} = 10\text{ V}$<br>(Resistive Load, Figure 3) |      | 35<br>360       |      | ns<br>ns       |
| $Q_g$<br>$Q_{gs}$<br>$Q_{gd}$ | Total Gate Charge<br>Gate-Source Charge<br>Gate-Drain Charge | $V_{DD} = 10\text{ V}$ $I_D = 120\text{ A}$ $V_{GS} = 10\text{ V}$                                                     |      | 125<br>40<br>50 | 150  | nC<br>nC<br>nC |

**SWITCHING OFF**

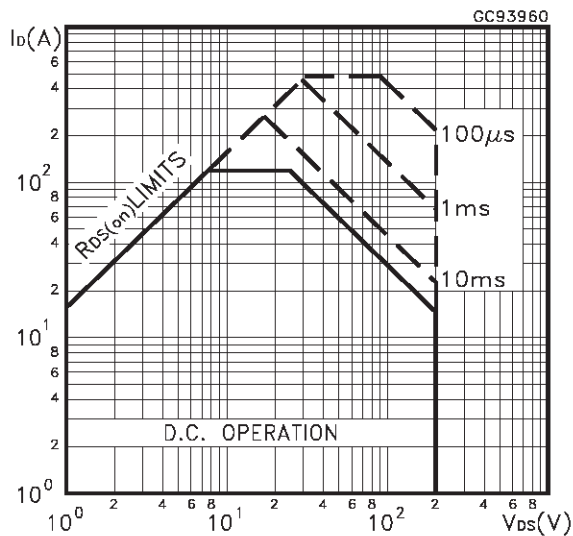
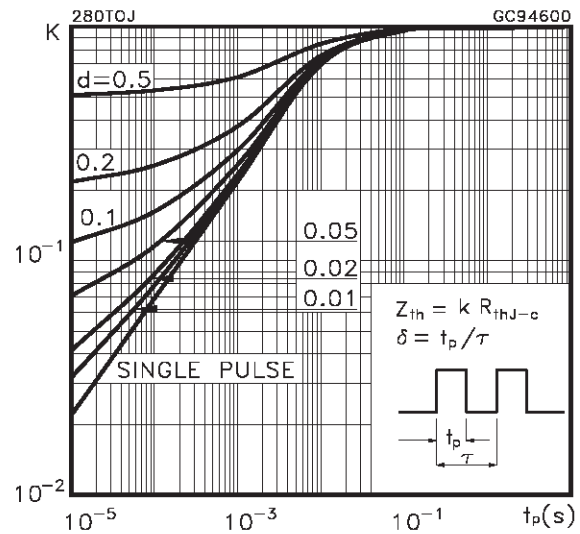
| Symbol                | Parameter                        | Test Conditions                                                                                                          | Min. | Typ.      | Max. | Unit     |
|-----------------------|----------------------------------|--------------------------------------------------------------------------------------------------------------------------|------|-----------|------|----------|
| $t_{d(off)}$<br>$t_f$ | Turn-off Delay Time<br>Fall Time | $V_{DD} = 10\text{ V}$ $I_D = 60\text{ A}$<br>$R_G = 4.7\ \Omega$ , $V_{GS} = 10\text{ V}$<br>(Resistive Load, Figure 3) |      | 75<br>110 |      | ns<br>ns |

**SOURCE DRAIN DIODE**

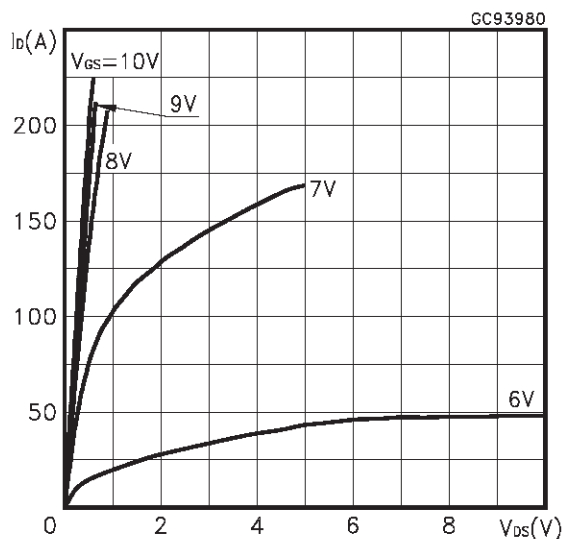
| Symbol                            | Parameter                                                                    | Test Conditions                                                                                                                                | Min. | Typ.             | Max.       | Unit          |
|-----------------------------------|------------------------------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------|------|------------------|------------|---------------|
| $I_{SD}$<br>$I_{SDM}^{(*)}$       | Source-drain Current<br>Source-drain Current (pulsed)                        |                                                                                                                                                |      |                  | 120<br>480 | A<br>A        |
| $V_{SD}^{(*)}$                    | Forward On Voltage                                                           | $I_{SD} = 120\text{ A}$ $V_{GS} = 0$                                                                                                           |      |                  | 1.3        | V             |
| $t_{rr}$<br>$Q_{rr}$<br>$I_{RRM}$ | Reverse Recovery Time<br>Reverse Recovery Charge<br>Reverse Recovery Current | $I_{SD} = 120\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$<br>$V_{DD} = 15\text{ V}$ $T_j = 150^\circ\text{C}$<br>(see test circuit, Figure 5) |      | 70<br>120<br>3.5 |            | ns<br>nC<br>A |

(\*) Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5 %.

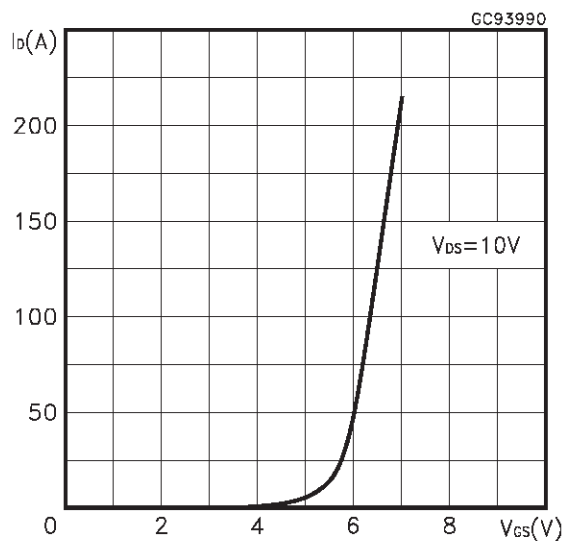
(●) Pulse width limited by safe operating area.

**Safe Operating Area****Thermal Impedance**

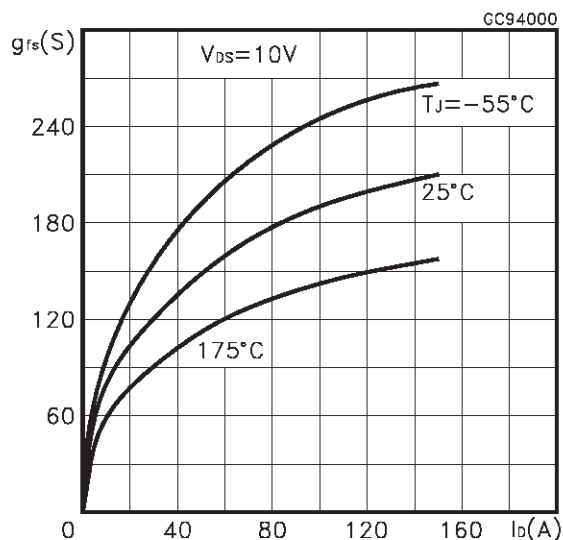
Output Characteristics



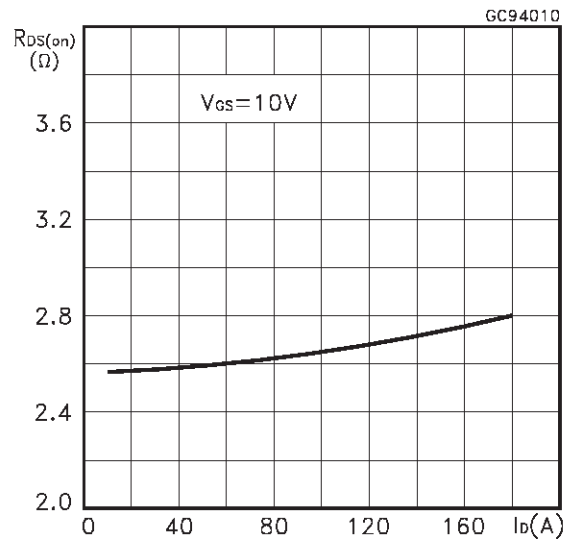
Transfer Characteristics



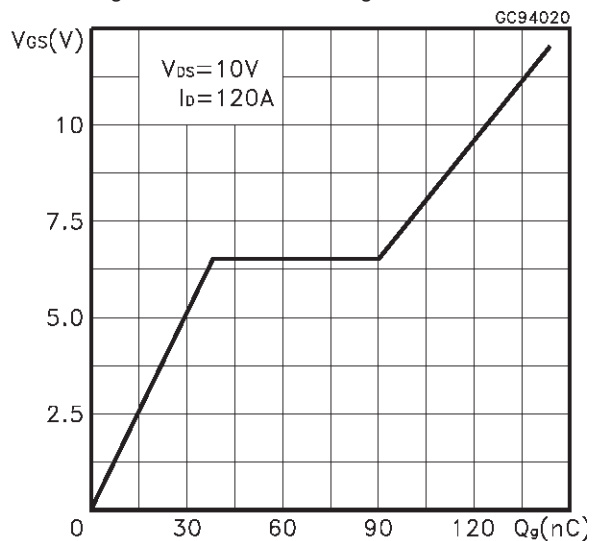
Transconductance



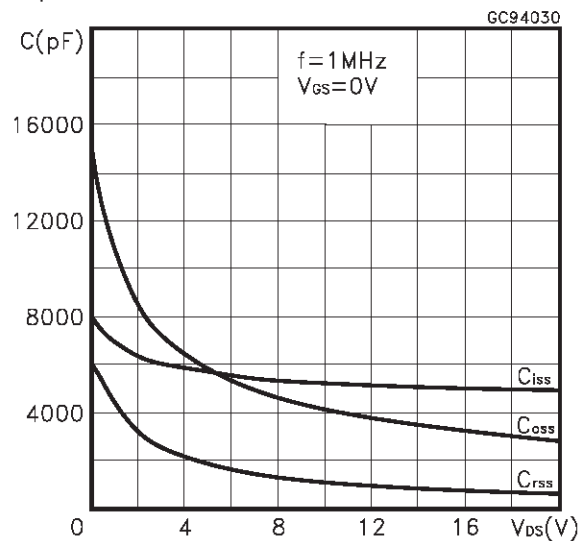
Static Drain-source On Resistance



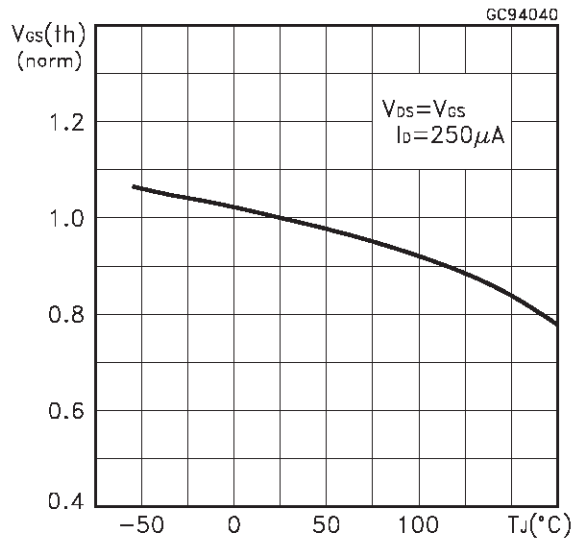
Gate Charge vs Gate-source Voltage



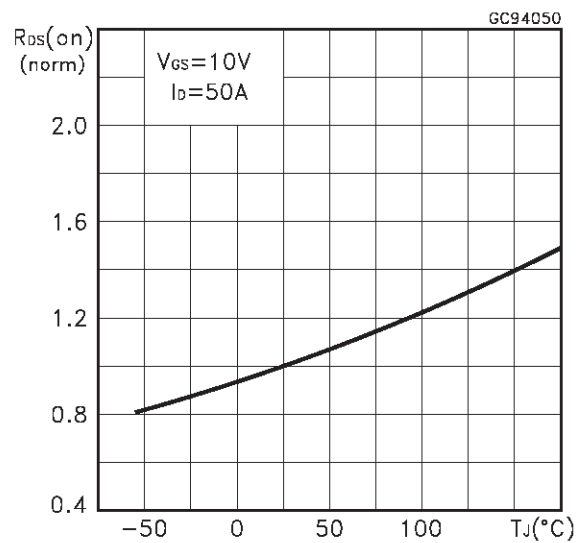
Capacitance Variations



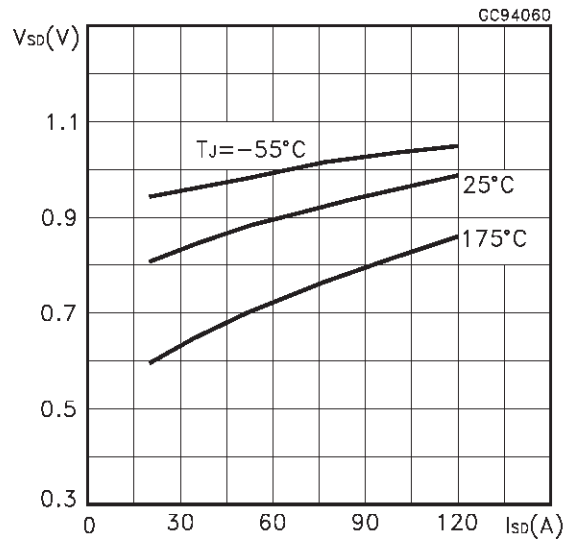
Normalized Gate Threshold Voltage vs Temperature



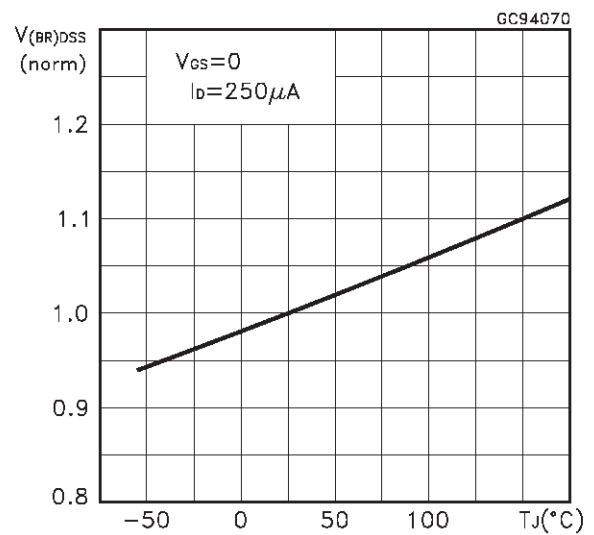
Normalized on Resistance vs Temperature



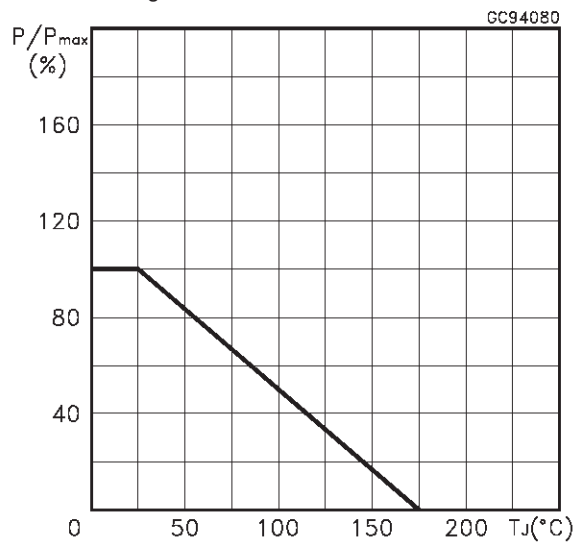
Source-drain Diode Forward Characteristics



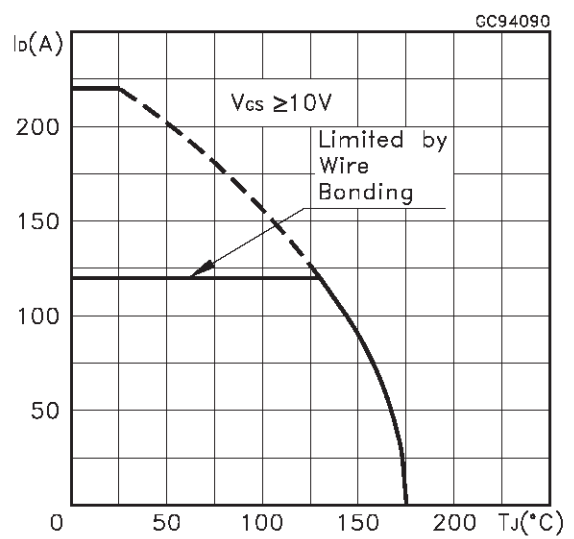
Normalized Breakdown Voltage vs Temperature.



Power Derating vs Tc

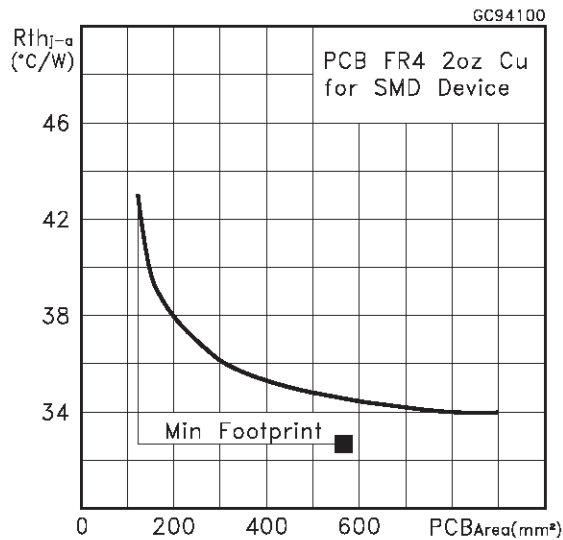


Max Id Current vs Tc

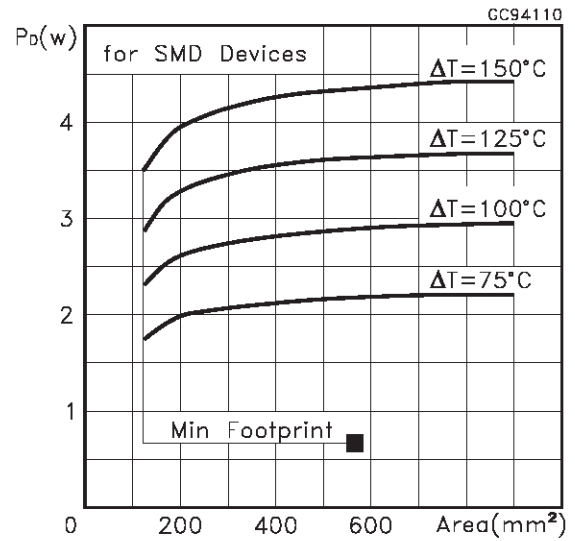


## STB210NF02/-1 STP210NF02

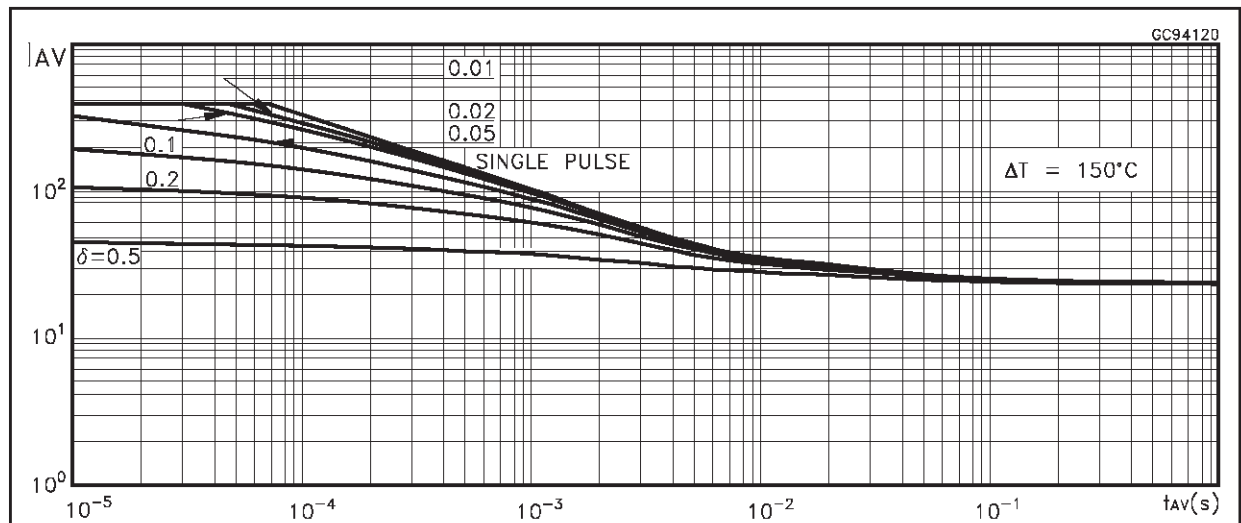
Thermal Resistance Rthj-a vs PCB Copper Area



Max Power Dissipation vs PCB Copper Area



Allowable Iav vs. Time in Avalanche



The previous curve gives the safe operating area for unclamped inductive loads, single pulse or repetitive, under the following conditions:

$$P_{D(AVE)} = 0.5 * (1.3 * BV_{DSS} * I_{AV})$$

$$E_{AS(AR)} = P_{D(AVE)} * t_{AV}$$

Where:

$I_{AV}$  is the Allowable Current in Avalanche

$P_{D(AVE)}$  is the Average Power Dissipation in Avalanche (Single Pulse)

$t_{AV}$  is the Time in Avalanche

To derate above 25 °C, at fixed  $I_{AV}$ , the following equation must be applied:

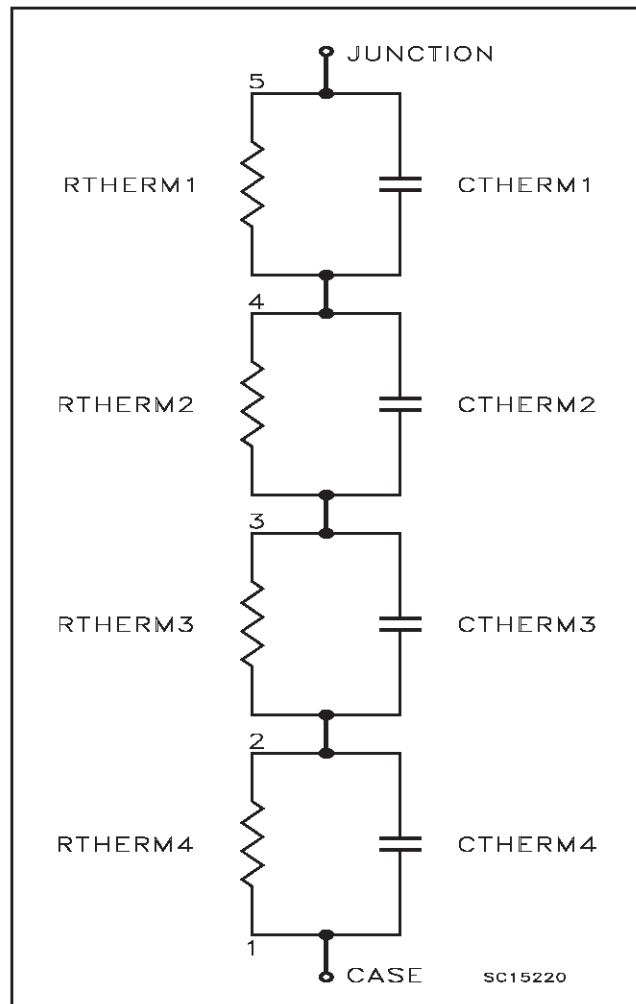
$$I_{AV} = 2 * (T_{jmax} - T_{CASE}) / (1.3 * BV_{DSS} * Z_{th})$$

Where:

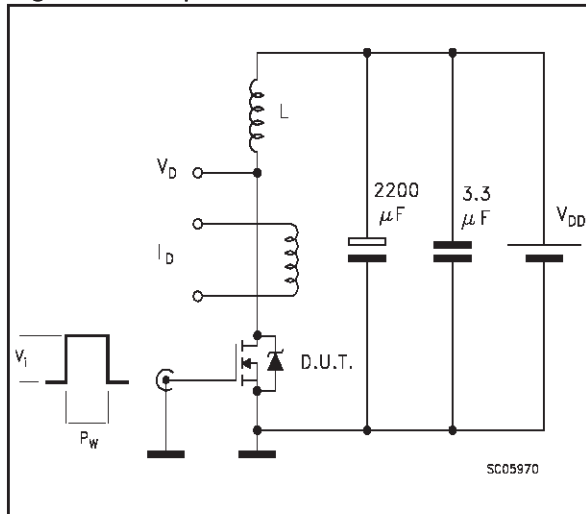
$Z_{th} = K * R_{th}$  is the value coming from Normalized Thermal Response at fixed pulse width equal to  $T_{AV}$ .

# SPICE THERMAL MODEL

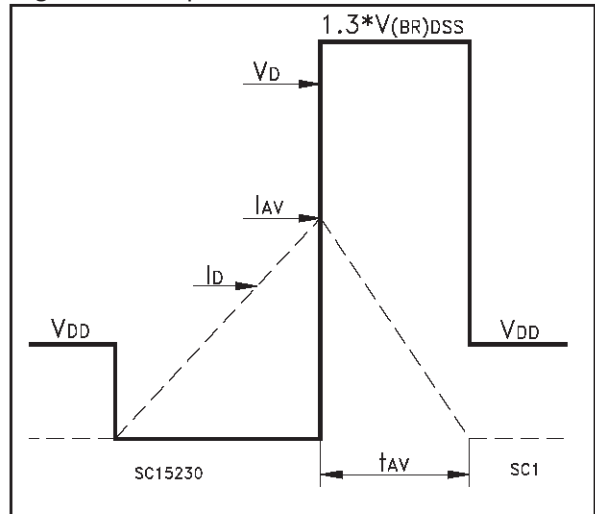
| Parameter | Node  | Value  |
|-----------|-------|--------|
| CTHERM1   | 5 - 4 | 0.011  |
| CTHERM2   | 4 - 3 | 0.0012 |
| CTHERM3   | 3 - 2 | 0.05   |
| CTHERM4   | 2 - 1 | 0.1    |
|           |       |        |
| R THERM1  | 5 - 4 | 0.09   |
| R THERM2  | 4 - 3 | 0.02   |
| R THERM3  | 3 - 2 | 0.11   |
| R THERM4  | 2 - 1 | 0.17   |



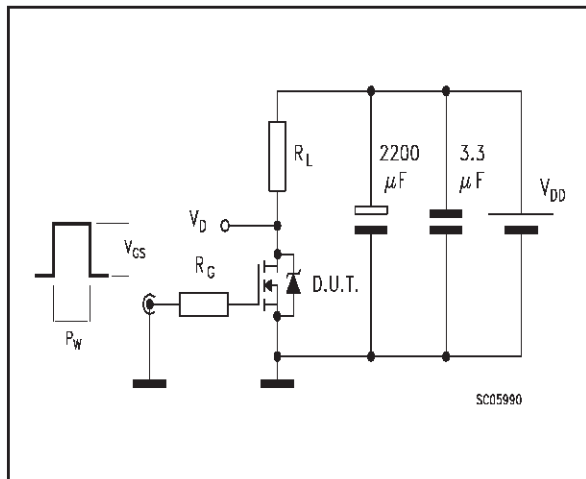
**Fig. 1:** Unclamped Inductive Load Test Circuit



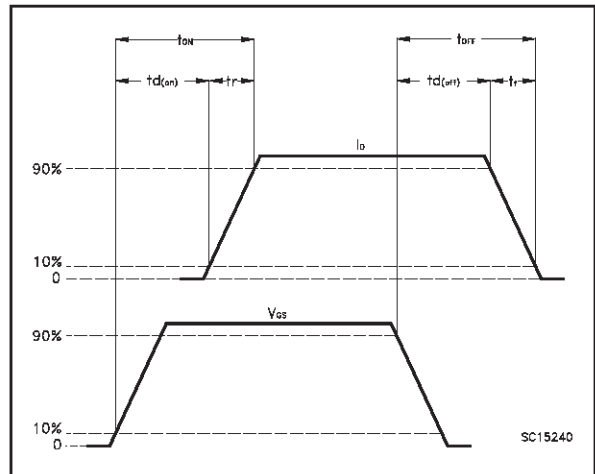
**Fig. 2:** Unclamped Inductive Waveform



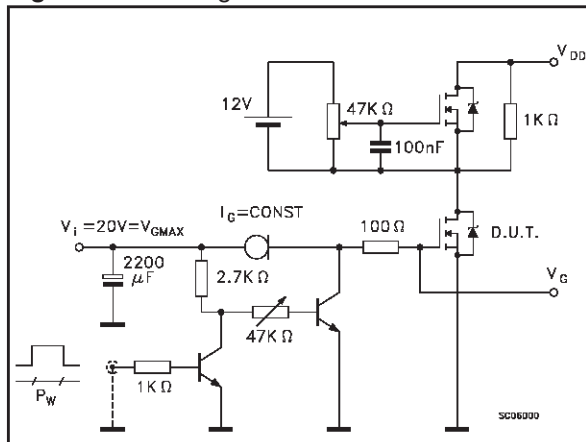
**Fig. 3:** Switching Times Test Circuits For Resistive Load



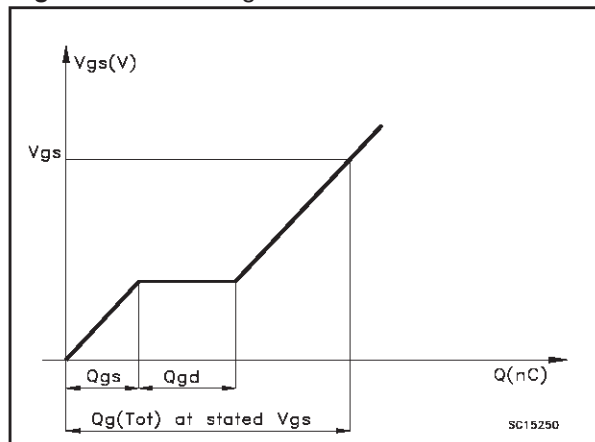
**Fig. 3.1:** Switching Time Waveform



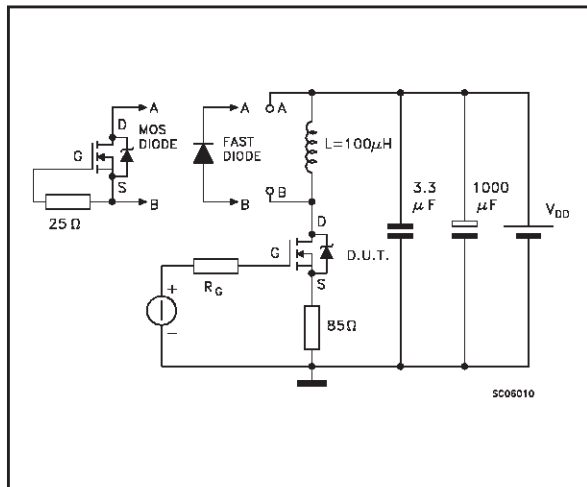
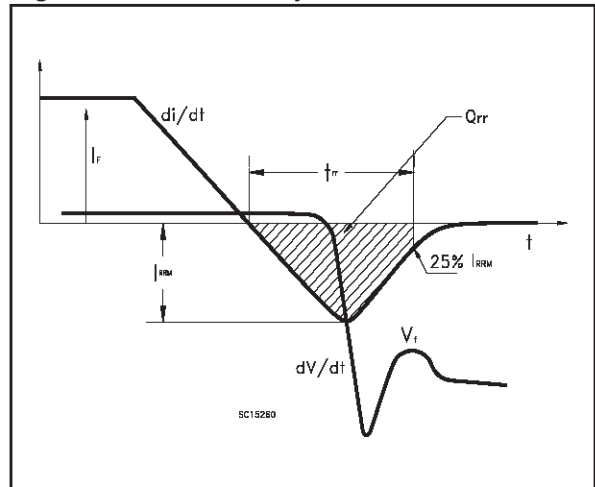
**Fig. 4:** Gate Charge Test Circuit



**Fig. 4.1:** Gate Charge Test Waveform

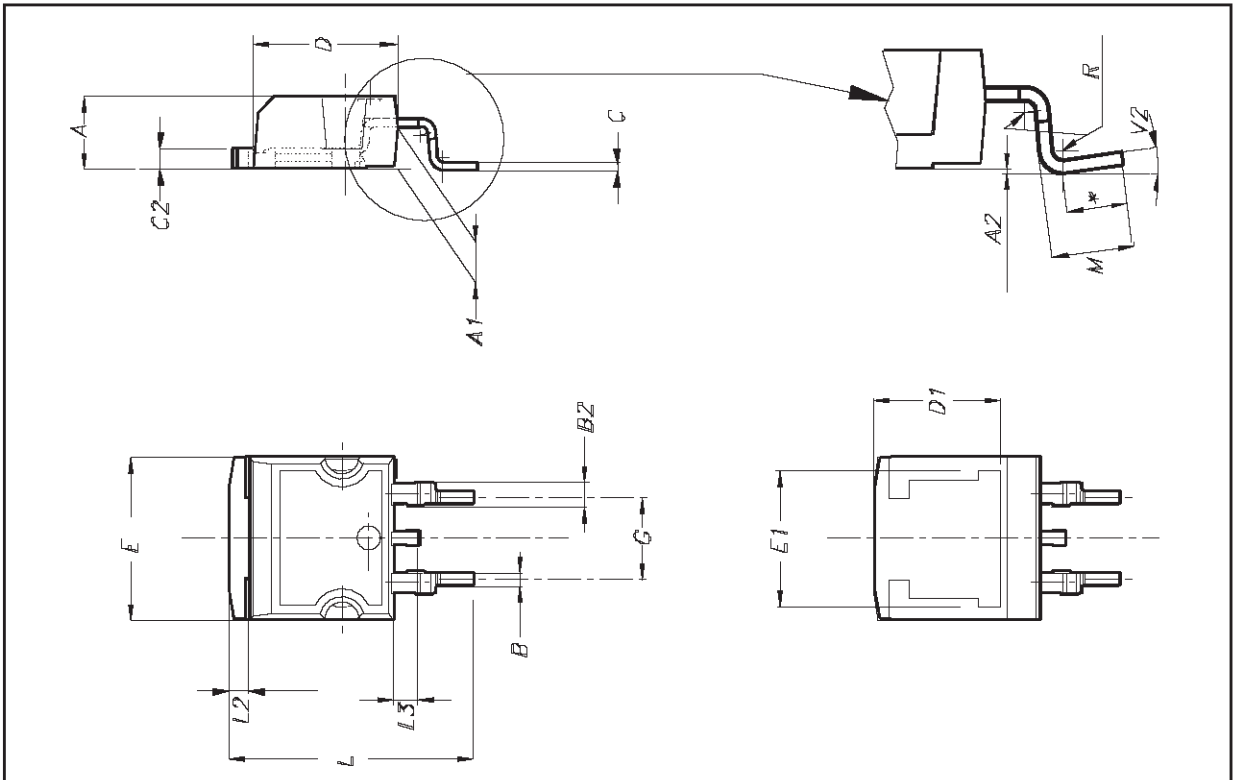




**Fig. 5:** Diode Switching Test Circuit**Fig. 5.1:** Diode Recovery Times Waveform

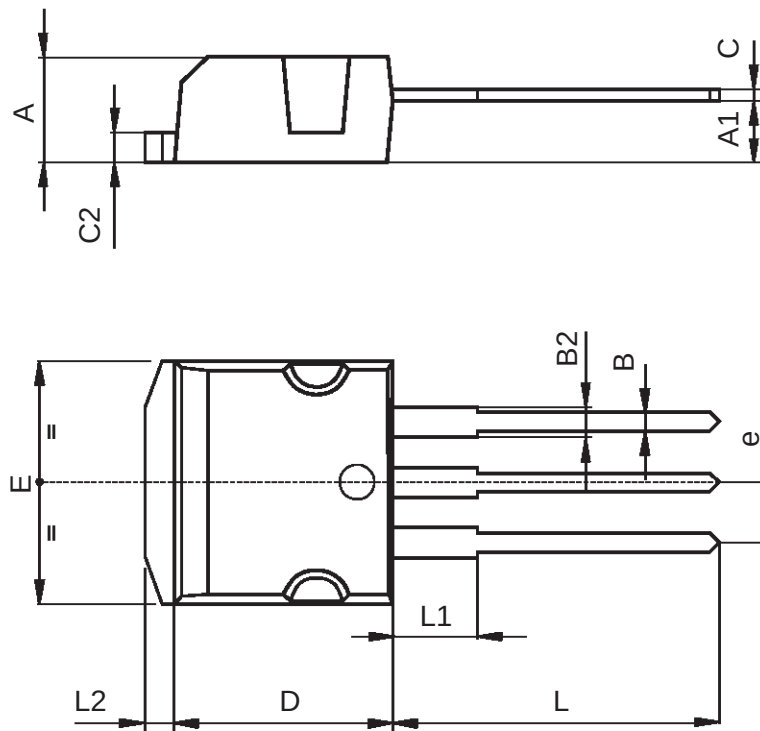
D PAK MECHANICAL DATA

| DIM. | mm.  |      |       | inch. |       |       |
|------|------|------|-------|-------|-------|-------|
|      | MIN. | TYP. | MAX.  | MIN.  | TYP.  | TYP.  |
| A    | 4.4  |      | 4.6   | 0.173 |       | 0.181 |
| A1   | 2.49 |      | 2.69  | 0.098 |       | 0.106 |
| A2   | 0.03 |      | 0.23  | 0.001 |       | 0.009 |
| B    | 0.7  |      | 0.93  | 0.028 |       | 0.037 |
| B2   | 1.14 |      | 1.7   | 0.045 |       | 0.067 |
| C    | 0.45 |      | 0.6   | 0.018 |       | 0.024 |
| C2   | 1.21 |      | 1.36  | 0.048 |       | 0.054 |
| D    | 8.95 |      | 9.35  | 0.352 |       | 0.368 |
| D1   |      | 8    |       |       | 0.315 |       |
| E    | 10   |      | 10.4  | 0.394 |       | 0.409 |
| E1   | 8.5  |      |       |       | 0.334 |       |
| G    | 4.88 |      | 5.28  | 0.192 |       | 0.208 |
| L    | 15   |      | 15.85 | 0.591 |       | 0.624 |
| L2   | 1.27 |      | 1.4   | 0.050 |       | 0.055 |
| L3   | 1.4  |      | 1.75  | 0.055 |       | 0.069 |
| M    | 2.4  |      | 3.2   | 0.094 |       | 0.126 |
| R    |      | 0.4  |       |       | 0.016 |       |
| V2   | 0°   |      | 8°    | 0°    |       | 8°    |



TO-262 (I<sup>2</sup>PAK) MECHANICAL DATA

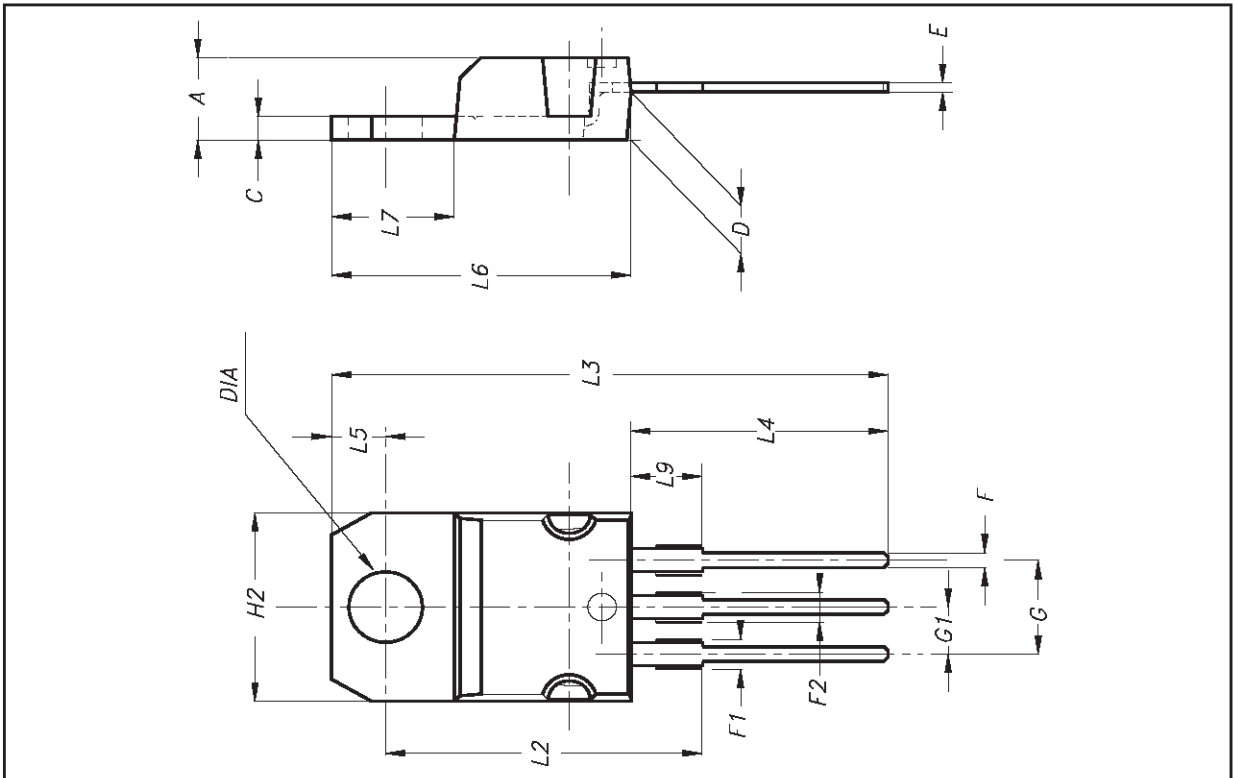
| DIM. | mm   |      |      | inch  |      |       |
|------|------|------|------|-------|------|-------|
|      | MIN. | TYP. | MAX. | MIN.  | TYP. | MAX.  |
| A    | 4.4  |      | 4.6  | 0.173 |      | 0.181 |
| A1   | 2.49 |      | 2.69 | 0.098 |      | 0.106 |
| B    | 0.7  |      | 0.93 | 0.027 |      | 0.036 |
| B2   | 1.14 |      | 1.7  | 0.044 |      | 0.067 |
| C    | 0.45 |      | 0.6  | 0.017 |      | 0.023 |
| C2   | 1.23 |      | 1.36 | 0.048 |      | 0.053 |
| D    | 8.95 |      | 9.35 | 0.352 |      | 0.368 |
| e    | 2.4  |      | 2.7  | 0.094 |      | 0.106 |
| E    | 10   |      | 10.4 | 0.393 |      | 0.409 |
| L    | 13.1 |      | 13.6 | 0.515 |      | 0.531 |
| L1   | 3.48 |      | 3.78 | 0.137 |      | 0.149 |
| L2   | 1.27 |      | 1.4  | 0.050 |      | 0.055 |

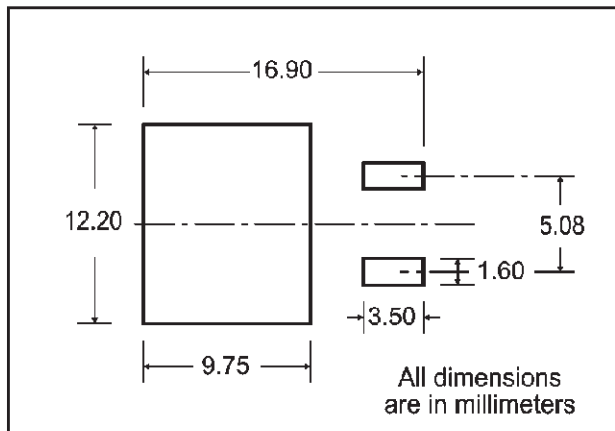
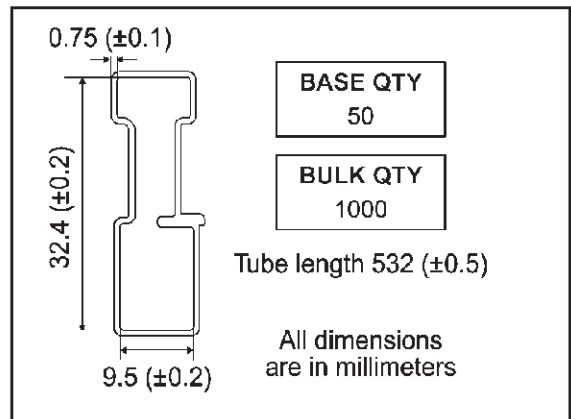
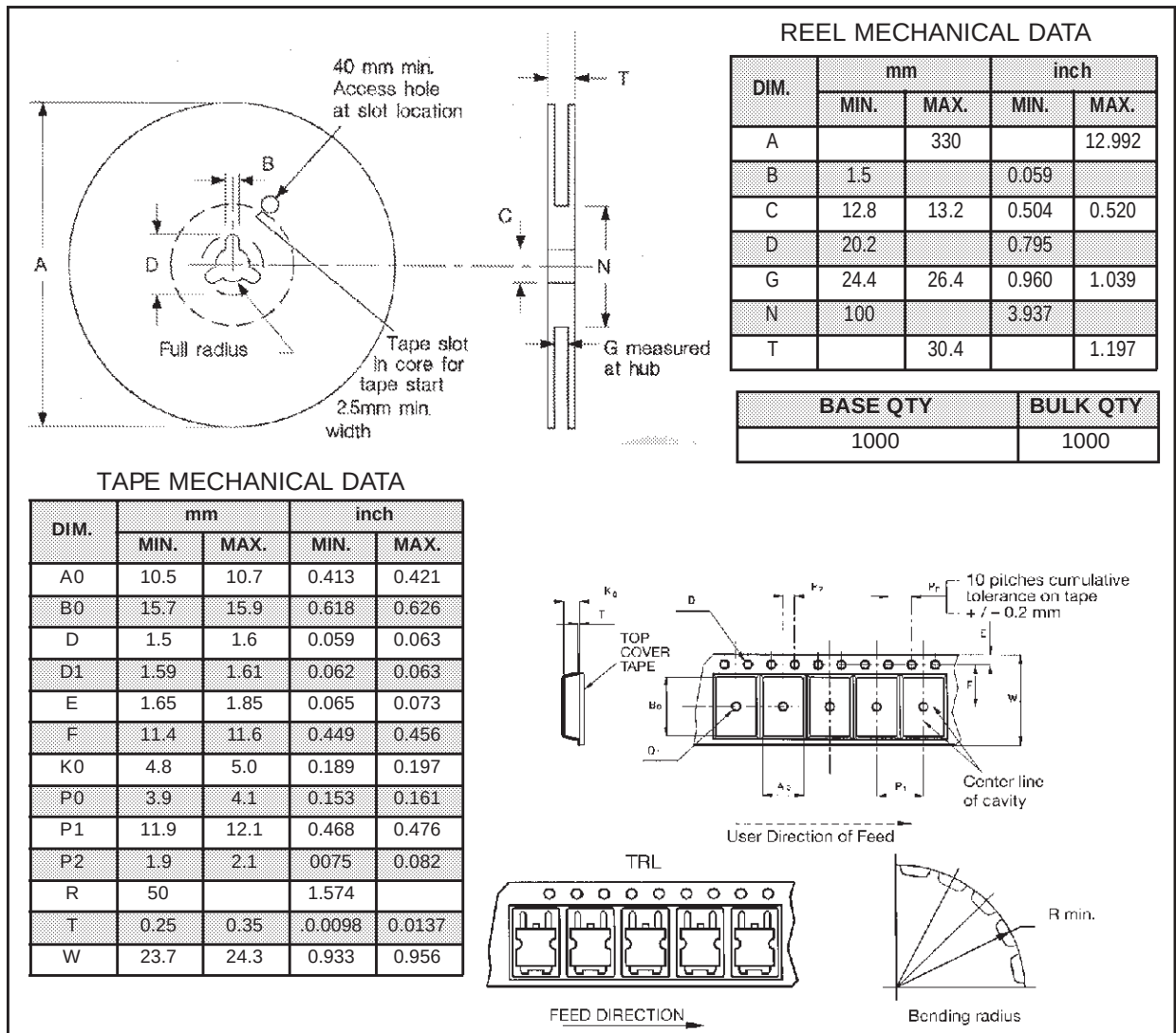


P011P5/E

TO-220 MECHANICAL DATA

| DIM. | mm.   |       |       | inch. |       |       |
|------|-------|-------|-------|-------|-------|-------|
|      | MIN.  | TYP.  | MAX.  | MIN.  | TYP.  | TYP.  |
| A    | 4.4   |       | 4.6   | 0.173 |       | 0.181 |
| C    | 1.23  |       | 1.32  | 0.048 |       | 0.051 |
| D    | 2.40  |       | 2.72  | 0.094 |       | 0.107 |
| E    | 0.49  |       | 0.70  | 0.019 |       | 0.027 |
| F    | 0.61  |       | 0.88  | 0.024 |       | 0.034 |
| F1   | 1.14  |       | 1.70  | 0.044 |       | 0.067 |
| F2   | 1.14  |       | 1.70  | 0.044 |       | 0.067 |
| G    | 4.95  |       | 5.15  | 0.194 |       | 0.203 |
| G1   | 2.40  |       | 2.70  | 0.094 |       | 0.106 |
| H2   | 10    |       | 10.40 | 0.393 |       | 0.409 |
| L2   |       | 16.40 |       |       | 0.645 |       |
| L3   |       | 28.90 |       |       | 1.137 |       |
| L4   | 13    |       | 14    | 0.511 |       | 0.551 |
| L5   | 2.65  |       | 2.95  | 0.104 |       | 0.116 |
| L6   | 15.25 |       | 15.75 | 0.600 |       | 0.620 |
| L7   | 6.20  |       | 6.60  | 0.244 |       | 0.260 |
| L9   | 3.50  |       | 3.93  | 0.137 |       | 0.154 |
| DIA  | 3.75  |       | 3.85  | 0.147 |       | 0.151 |



**D<sup>2</sup>PAK FOOTPRINT****TUBE SHIPMENT (no suffix)\*****TAPE AND REEL SHIPMENT (suffix "T4")\***

\* on sales type

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